## ABSTRACT

# METHOD AND APPARATUS FOR REDUCING WARPAGE IN SEMICONDUCTOR PACKAGES

An apparatus and method for reducing warpage in semiconductor packages, and in particular, thin quad flat packages (TQFPs). The apparatus includes a clamping jig having a bottom plate and an upper plate. The bottom plate is connected to a heater which heats the plate to approximately 50 to 70 degrees Celsius. An air supply controller delivers air supply to the upper plate. The TQFPs are placed in between the bottom plate and the upper plate immediately after they have been encapsulated with resin and the resin has cured. The clamping jig clamps the TQFPs in between the bottom and upper plate with a slight force. The TQFPs remain in the clamping jig until they have sufficiently cooled.

FIG. 5